iNEMI

International Electronics Manufacturing Initiative

Optimizing Lead-Free Processes

Free Forum

FO1
APEX 2007
February 20, 2007

Advancing manufacturing technology

Agenda

F01 iNEMI Optimizing Lead-Free Processes Free Forum

1:30 p.m. - 1:40 p.m. Introduction: Bob Pfahl, iNEMI

1:40 p.m. - 2:35 p.m. iNEMI Pb-Free Projects Update:

- **1:40 - 2:00** Pb-Free Wave Soldering Project: Project: Denis Barbini, Vitronics Soltec, Chair, Paul Wang, Microsoft, Co-Chair
- **2:00 - 2:15** Lead-Free Rework Optimization Project: Jasbir Bath, Solectron
- **2:15 - 2:35** Pb-Free BGAs in SnPb Assembly Project:

  Robert Kinyanjui, Sanmina-SCI, Chair, Quyen Chu, Jabil Circuit, Inc., Co-Chair

2:35 p.m. – 2:45 p.m. iNEMI High-Reliability RoHS Task Force Update
Mike Davisson, Agilent Technologies

2:45 p.m. – 2:55 p.m. Pb-free Component & Board Finish Reliability Project
“ Call for Participation” : Richard J. Coyle, Alcatel-Lucent

2:55 p.m. - 3:00 p.m. Open Discussion

Bifurcation of Pb-Free Activities

- **Consumer Products**
  - **Optimize Processes and Materials**
  - **Reduce Cost**
  - **Increase Yield and Throughput**
- **High-Reliability Products**
  - **Taking the Pb exemption has changed the risk profile for High Reliability producers.**
  - **The components supply chain has rapidly converted to RoHS compliant offerings (Pb-free) with little motivation to continue to produce SnPb product.**
  - **Activities are underway to provide the industry with better understanding of Pb-free risks in high-reliability applications**
  - **Initiatives are being developed to understand and resolve risks**